



Staff Component/Reliability Engineer	<i>Signature Here</i>
Sr. Principal Component Quality Engineer	<i>Signature Here</i>

CHIPSID GOLDEN SAMPLE REFERENCE REPORT

Part Information	
Part Number:	XXXXXX-XXXXXX
Manufacturer:	STMicroelectronics
Description:	IC EEPROM 2KBIT I2C 8TSSOP
Date Code:	2134
Country of Origin:	MALAYSIA

This report includes the following images of the reference part to assist with counterfeit mitigation:

- 1) Top View
- 2) Bottom View
- 3) Component Leads
- 4) X-Ray Topography
- 5) Die Topography (Dark Field)
- 6) Die Topography (Bright Field)

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Top View



Bottom View



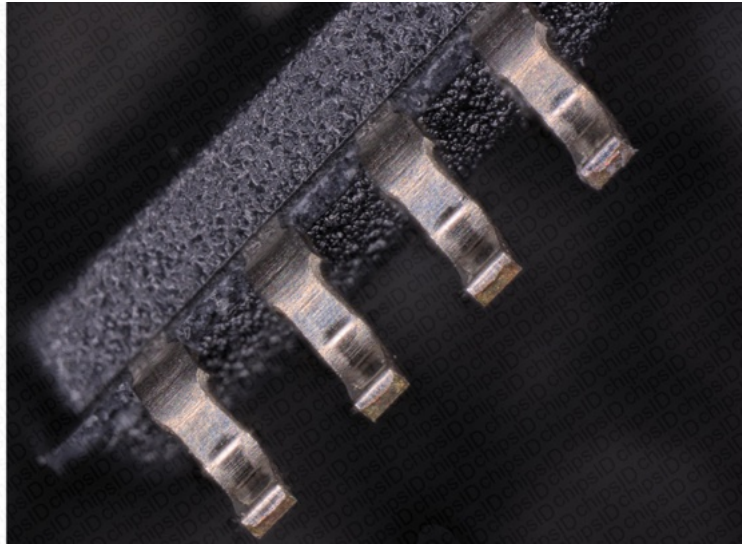
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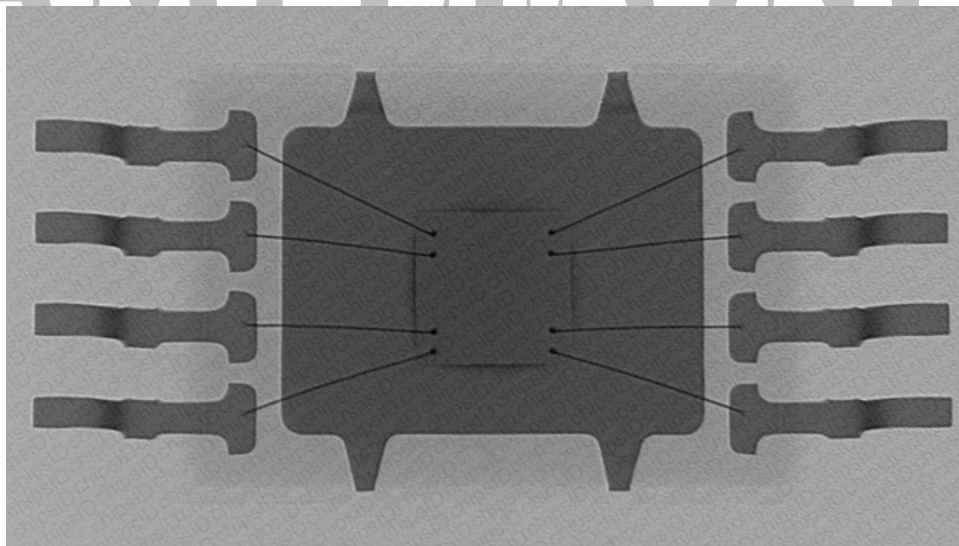


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Component Leads



X-Ray Topography



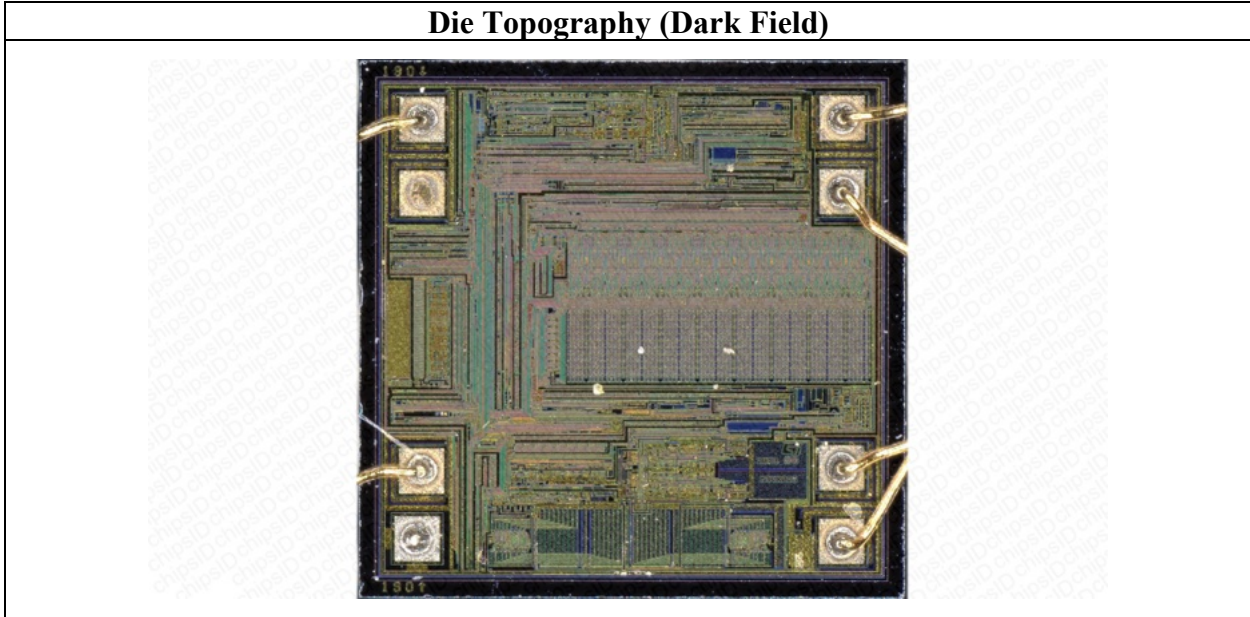
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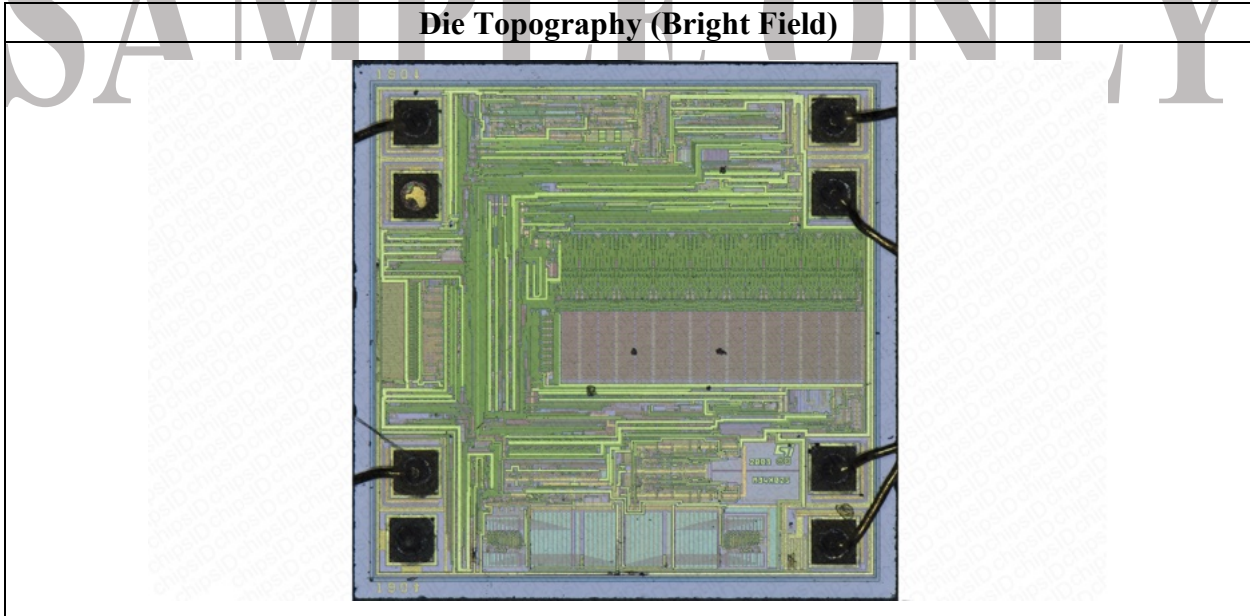


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Die Topography (Dark Field)



Die Topography (Bright Field)



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